

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
6 April 2006 (06.04.2006)

PCT

(10) International Publication Number
WO 2006/036282 A1

(51) International Patent Classification:
H05K 1/02 (2006.01)

(21) International Application Number:
PCT/US2005/026688

(22) International Filing Date: 27 July 2005 (27.07.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/817,785 17 September 2004 (17.09.2004) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM,

AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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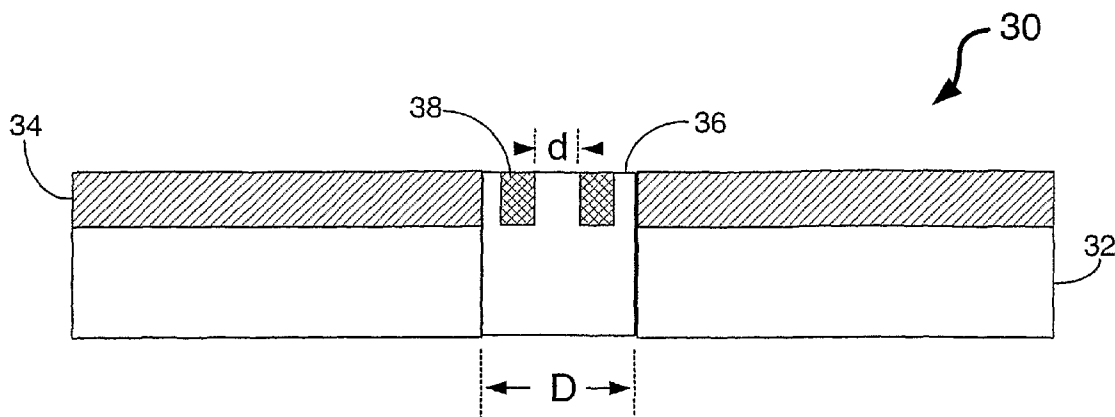
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Published:

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(54) Title: CIRCUIT BOARD ASSEMBLY WITH REDUCED CAPACITIVE COUPLING



(57) Abstract: A circuit board structure is disclosed. The structure includes a flat substrate having oppositely disposed planar surfaces and a conductor. The conductor is formed on at least one of the planar surfaces and defines a conductor plane. The structure further includes an oversized-in-diameter anti-pad formed through the substrate layer and the conductor layer. The anti-pad further includes a spacer formed substantially coplanar with the conductor plane.